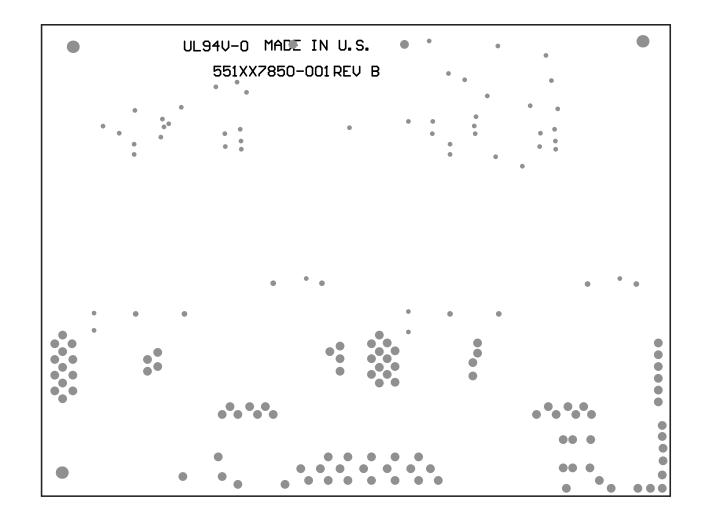


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	PROJECT NAME = PMP7850 REVB					
LAYER NAME = Top Owedeay	ARTWORK # = 880XX7850-001 REV B		TEXAS INSTRUMENTS			
PLOT NAME = Top Assembly Drawing		GENERATED : 4	10/2015	5:40:18 PM		



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	PROJECT NAME = PMP7850 REVB				
LAYER NAME =	ARTWORK #88 = 880XX7850-001	REV B	heąpą	I VIEL XIAS I ENEST	RUMENTS
PLOT NAME = Bottom Assembly Drawing		GENERATED	: 4	/10/2015	5:40:19 PM

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